

EUROPEAN PATENT OFFICE

Patent Abstracts of Japan

PUBLICATION NUMBER : 09057749
PUBLICATION DATE : 04-03-97

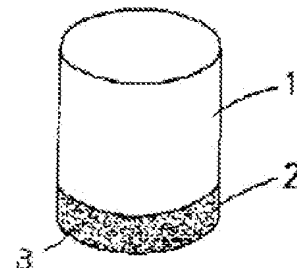
APPLICATION DATE : 25-08-95
APPLICATION NUMBER : 07216923

APPLICANT : MATSUSHITA ELECTRIC WORKS LTD;

INVENTOR : HASHIMOTO SHINJI;

INT.CL. : B29B 9/12 B29C 45/02 B29C 45/14
B32B 27/26 H01L 21/56 // B29K 63:00
B29K503:04

TITLE : EPOXY RESIN TABLET FOR SEALING



ABSTRACT : PROBLEM TO BE SOLVED: To provide an epoxy resin tablet for sealing having an excellent mold releasing property with a plunger or mold even in the event of repeating a molding operation, besides, capable of obtaining a sealing layer with a fine moisture proofing reliability when sealing is conducted by transfer molding.

SOLUTION: This cylindrical, polygonal columnar tablet comprises a multi-layer structure. The multi-layer contains an epoxy resin, a curing agent, and an inorganic filler as components, and has a first layer 1 consisting of an epoxy resin composition of an inorganic filler content of 70-90vol.%, and a second layer 2 containing as components an epoxy resin, a curing agent, and a mold releasing agent, and consisting of an epoxy resin composition having a higher mold releasing property than that of the first layer 1. Furthermore, it forms an outer layer 3 at the side where the second layer 2 is in contact with the plunger of a transfer molding machine.

COPYRIGHT: (C)1997,JPO